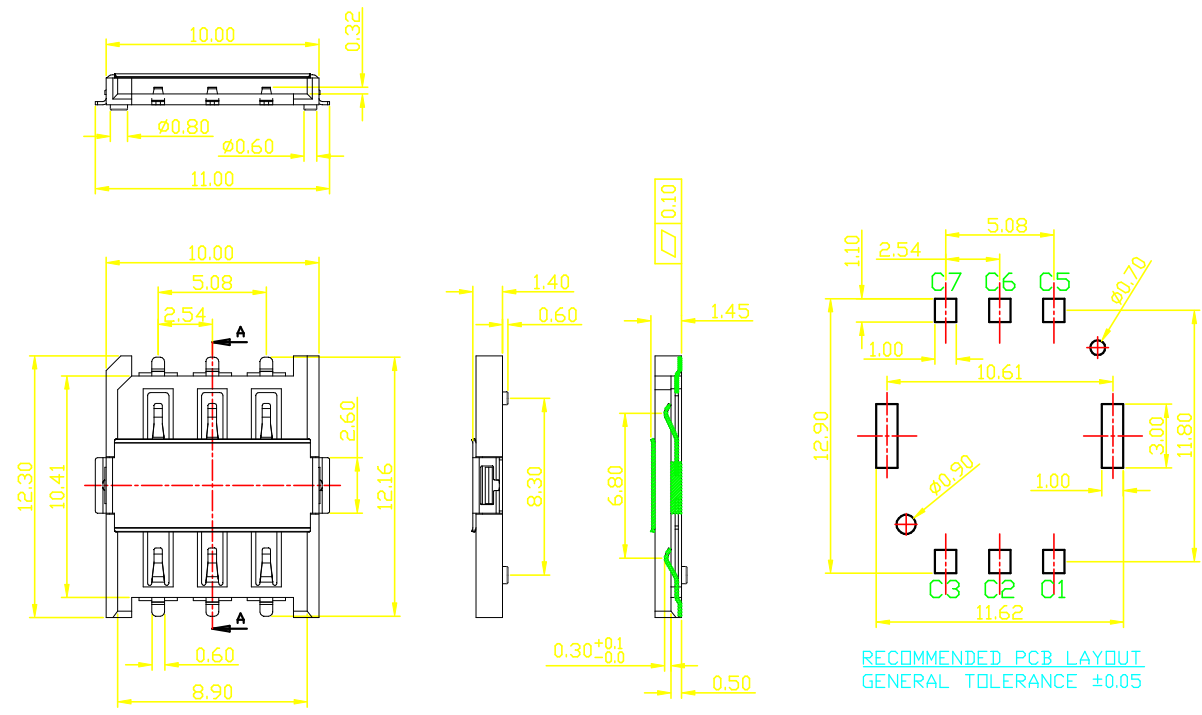
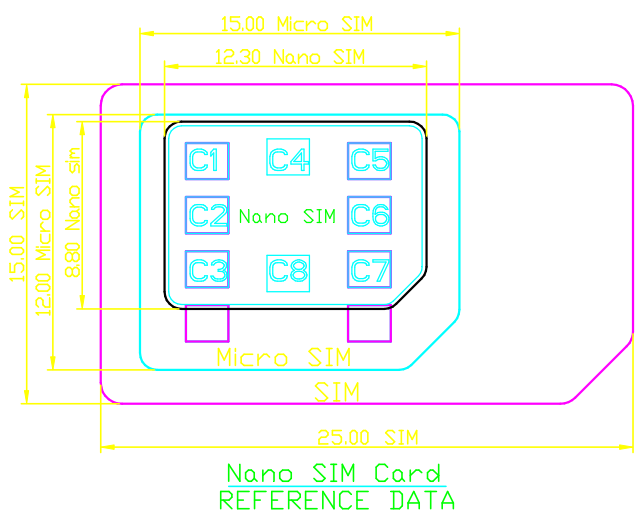


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2014/12/29



SECTION: A-A

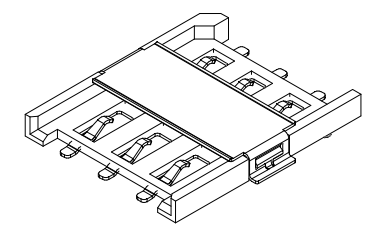
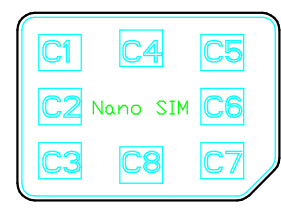


- C1 --> VCC
- C2 --> RST
- C3 --> CLK
- C5 --> GND
- C6 --> VPP
- C7 --> I/O

Notes:

- 1.Material:
 - Housing: LCP 30%GF, UL94V-0, Black
 - Contact : Phosphor Bronze, T=0.15mm
 - Shell: SUS304-H, T=0.15mm
- 2.Plating:
 - Contact:
 - Contact Area: 3U" GOLD PLATED
 - Solder Area: G/F Gold
 - Underplating: Ni overall 50u" Min.
 - Shell:
 - Solder Area: G/F Gold
 - Underplating: Ni overall 50u"
- 3.Mechanical:
 - Life cycles: 5000.
- 4.Electrical:
 - Voltage Rating: 30V AC RMS
 - Current Rating: 0.5A AC RMS Max
 - Operating Temperature: -20°C to +80°C
 - Dielectric Withstanding Voltage: 100V AC (60Sec Min)
 - Insulation Resistance: 100MΩ Min
 - Contact Resistance: 30mΩ Max

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

GENERAL TOLERANCE		EDWG NO.	A1229-001		APPD:	WIND	Scale	1:1
X.±0.45	x.°±5°	Title	NANO SIM SOCKET 6PIN 1.45H		CHKD:		UNIT	mm
.X±0.35	.x°±2°		DR:					
.XX±0.25	.xx°±1°	Part NO.	WL-SIM145-084		Date	2014/12/29		
.XXX±0.15	.xxx°±0.5°	深圳市微连电子有限公司 Shenzhen Welink Electronics Co.,Ltd						
SHEET	1/1							